

# ORDER FORM

Name: \_\_\_\_\_  
Position: \_\_\_\_\_  
Company: \_\_\_\_\_  
Ship to Address: \_\_\_\_\_  
\_\_\_\_\_

Date: \_\_\_\_\_  
Telephone: \_\_\_\_\_  
Fax: \_\_\_\_\_  
Bill to Address: \_\_\_\_\_  
\_\_\_\_\_

Email address (for delivery of electronic copies): \_\_\_\_\_

Purchase Order Number: \_\_\_\_\_

AMEX, Visa, MC: \_\_\_\_\_ Exp. Date: \_\_\_\_\_ CVV Number: \_\_\_\_\_

Report Price: \$ \_\_\_\_\_

Total Amount: \$ \_\_\_\_\_

## Quantity

\_\_\_\_\_ 2022 Flip Chip and WLP: Trends and Market Forecasts  
October 2022 (corporate license \$9,000)

\_\_\_\_\_ Advanced Packaging Update: Market and Technology Trends (4 issues)  
(corporate license \$8,750, single issue \$2,500)

\_\_\_\_\_ Quantifying the Impact of Heterogeneous Integration: Chiplets and SiP  
February 2021 (corporate license \$8,750)

\_\_\_\_\_ New Packages and Materials for Power Devices  
October 2018 (corporate license \$8,750)

\_\_\_\_\_ New Frontiers in Automotive Electronics Packaging  
January 2018 (corporate license \$8,750)

\_\_\_\_\_ 2023 Global Semiconductor Packaging Materials Outlook  
(call for pricing)

\_\_\_\_\_ Worldwide Assembly and Test Facility  
(call for pricing)

\_\_\_\_\_ SavanSys Fan-Out Wafer Level Packaging Cost Analysis  
(\$3,995 single user, corporate license \$7,000)

\_\_\_\_\_ SavanSys Cost Models for Packaging:  Wire Bond,  Flip Chip,  WLP  
(\$5,750 each—annual fee, single user; corporate license \$12,500)

### TechSearch Teardowns

- \_\_\_\_\_  Google-Pixel 7 with 5G mmWave  
 Apple iPhone 14 Pro  
 Xiaomi Mi 12  
 Samsung Galaxy Watch5  
 Apple Watch Series 5 GPS+LTE  
 Samsung Electronics Galsxy S23 Ultra 5G



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